

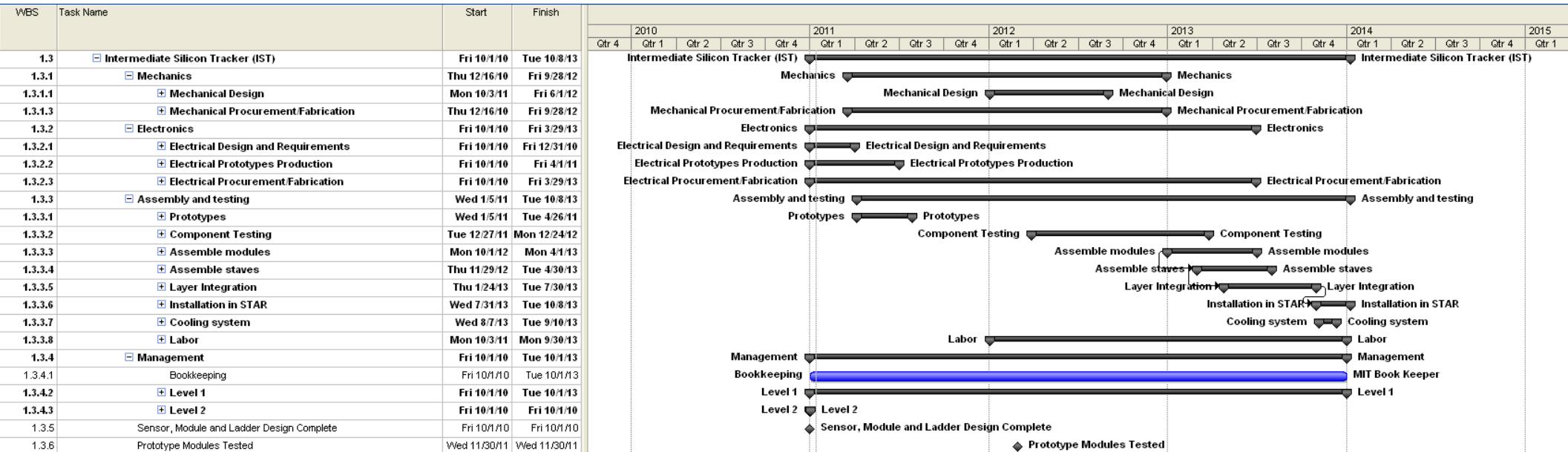
IST cost, schedule, plans, report

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HFT-TC Quarterly Meeting  
BNL, October 14, 2010

# IST WBS: Cost

		WBS	Task Name	Start	Finish	Participating Institutions	Cost	Redirected	Tech Risk	Cost Risk	Schedule Risk	Design Risk	Tech Weight	Cost weight	Calculated Contingency %	Calculated Contingency \$	Base Cost + Contingency Cost
475		1.3	☐ Intermediate Silicon Tracker (IST)	Fri 10/1/10	Tue 10/8/13	MIT	\$2,208,674.43	No	0	0	0	0	0	0	0	\$446,412.81	\$2,655,087.24
476		1.3.1	☐ Mechanics	Thu 12/16/10	Fri 9/28/12	MIT	\$397,618.60	No	0	0	0	0	0	0	0	\$130,944.20	\$528,562.80
477		1.3.1.1	+ Mechanical Design	Mon 10/3/11	Fri 6/1/12	MIT	\$81,116.48	No	0	0	0	0	0	0	0	\$26,964.24	\$108,080.72
481		1.3.1.3	+ Mechanical Procurement/Fabrication	Thu 12/16/10	Fri 9/28/12	MIT	\$316,502.12	No	0	0	0	0	0	0	0	\$103,979.96	\$420,482.08
488		1.3.2	☐ Electronics	Fri 10/1/10	Fri 3/29/13	MIT	\$1,201,259.68	No	0	0	0	0	0	0	0	\$315,468.61	\$1,516,728.29
489		1.3.2.1	+ Electrical Design and Requirements	Fri 10/1/10	Fri 12/31/10	MIT	\$113,657.28	No	0	0	0	0	0	0	0	\$40,916.62	\$154,573.90
505		1.3.2.2	+ Electrical Prototypes Production	Fri 10/1/10	Fri 4/1/11	MIT	\$125,300.00	No	0	0	0	0	0	0	0	\$25,627.00	\$150,927.00
509		1.3.2.3	+ Electrical Procurement/Fabrication	Fri 10/1/10	Fri 3/29/13	MIT	\$962,302.40	No	0	0	0	0	0	0	0	\$248,924.99	\$1,211,227.39
530		1.3.3	☐ Assembly and testing	Wed 1/5/11	Tue 10/8/13	MIT	\$504,392.30	No	0	0	0	0	0	0	0	\$0.00	\$504,392.30
531		1.3.3.1	+ Prototypes	Wed 1/5/11	Tue 4/26/11	MIT	\$20,236.80	No	0	0	0	0	0	0	0	\$0.00	\$20,236.80
535		1.3.3.2	+ Component Testing	Tue 12/27/11	Mon 12/24/12	MIT	\$39,916.80	No	0	0	0	0	0	0	0	\$0.00	\$39,916.80
557		1.3.3.3	+ Assemble modules	Mon 10/1/12	Mon 4/1/13	MIT	\$93,754.08	No	0	0	0	0	0	0	0	\$0.00	\$93,754.08
563		1.3.3.4	+ Assemble staves	Thu 11/29/12	Tue 4/30/13	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
567		1.3.3.5	+ Layer Integration	Thu 1/24/13	Tue 7/30/13	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
574		1.3.3.6	+ Installation in STAR	Wed 7/31/13	Tue 10/8/13	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
577		1.3.3.7	+ Cooling system	Wed 8/7/13	Tue 9/10/13	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
580		1.3.3.8	+ Labor	Mon 10/3/11	Mon 9/30/13	MIT	\$350,484.62	No	0	0	0	0	0	0	0	\$0.00	\$350,484.62
585		1.3.4	☐ Management	Fri 10/1/10	Tue 10/1/13	MIT	\$105,403.85	No	0	0	0	0	0	0	0	\$0.00	\$105,403.85
586		1.3.4.1	Bookkeeping	Fri 10/1/10	Tue 10/1/13	MIT	\$105,403.85	No	0	0	0	0	0	0	0	\$0.00	\$105,403.85
587		1.3.4.2	+ Level 1	Fri 10/1/10	Tue 10/1/13	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
593		1.3.4.3	+ Level 2	Fri 10/1/10	Fri 10/1/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
602		1.3.5	Sensor, Module and Ladder Design Complete	Fri 10/1/10	Fri 10/1/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
603		1.3.6	Prototype Modules Tested	Wed 11/30/11	Wed 11/30/11	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00

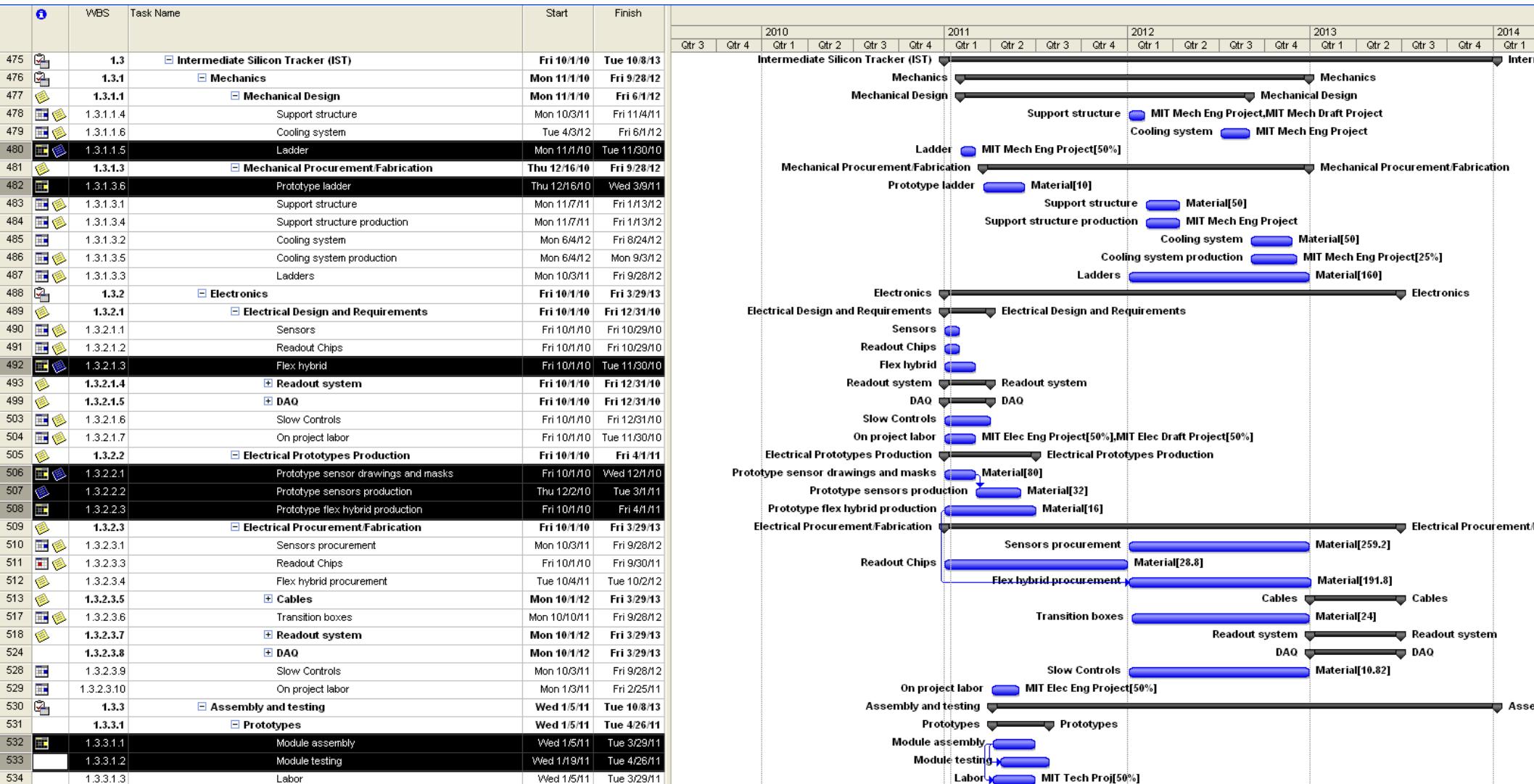
# IST WBS:Schedule



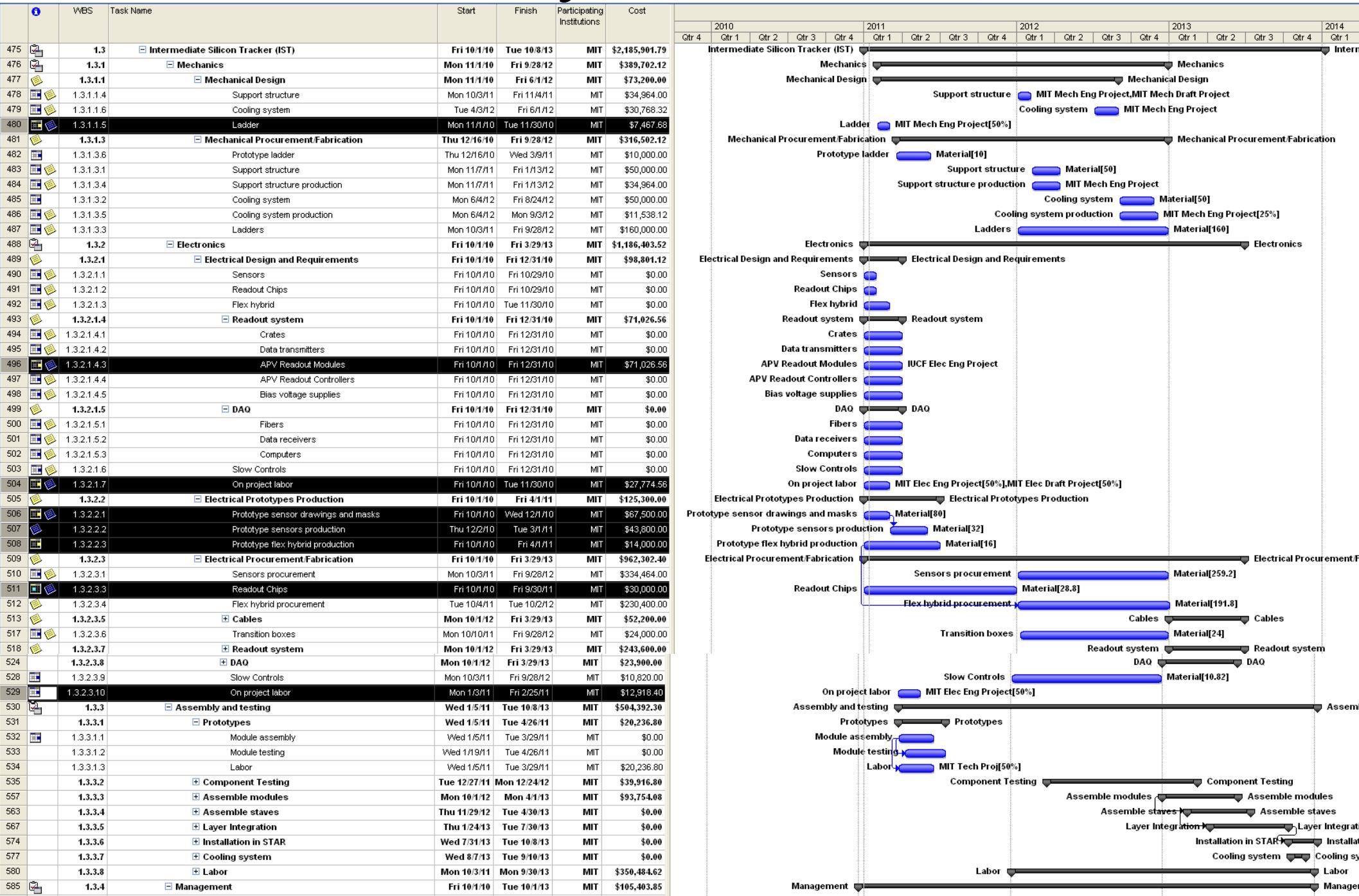
# IST WBS: Risk & Contingencies

		WBS	Task Name	Start	Finish	Participating Institutions	Cost	Redirected	Tech Risk	Cost Risk	Schedule Risk	Design Risk	Tech Weight	Cost weight	Calculated Contingency %	Calculated Contingency \$	Base Cost + Contingency Cost
475		1.3	Intermediate Silicon Tracker (IST)	Fri 10/1/10	Tue 10/8/13	MIT	\$2,185,901.79	No	0	0	0	0	0	0	0	\$438,372.99	\$2,624,274.78
476		1.3.1	Mechanics	Mon 11/1/10	Fri 9/28/12	MIT	\$389,702.12	No	0	0	0	0	0	0	0	\$128,252.59	\$517,954.71
477		1.3.1.1	Mechanical Design	Mon 11/1/10	Fri 6/1/12	MIT	\$73,200.00	No	0	0	0	0	0	0	0	\$24,272.63	\$97,472.63
478		1.3.1.1.4	Support structure	Mon 10/3/11	Fri 11/4/11	MIT	\$34,964.00	No	8	3	4	8	2	2	34	\$11,887.76	\$46,851.76
479		1.3.1.1.6	Cooling system	Tue 4/3/12	Fri 6/1/12	MIT	\$30,768.32	No	4	6	4	8	2	2	32	\$9,845.86	\$40,614.18
480		1.3.1.1.5	Ladder	Mon 11/1/10	Tue 11/30/10	MIT	\$7,467.68	No	6	3	8	8	2	2	34	\$2,539.01	\$10,006.69
481		1.3.1.3	Mechanical Procurement/Fabrication	Thu 12/16/10	Fri 9/28/12	MIT	\$316,502.12	No	0	0	0	0	0	0	0	\$103,979.96	\$420,482.08
482		1.3.1.3.6	Prototype ladder	Thu 12/16/10	Wed 3/9/11	MIT	\$10,000.00	No	1	4	4	0	2	1	10	\$1,000.00	\$11,000.00
483		1.3.1.3.1	Support structure	Mon 11/7/11	Fri 1/13/12	MIT	\$50,000.00	No	8	3	4	8	2	2	34	\$17,000.00	\$67,000.00
484		1.3.1.3.4	Support structure production	Mon 11/7/11	Fri 1/13/12	MIT	\$34,964.00	No	8	3	4	8	2	2	34	\$11,887.76	\$46,851.76
485		1.3.1.3.2	Cooling system	Mon 6/4/12	Fri 8/24/12	MIT	\$50,000.00	No	4	6	4	8	2	2	32	\$16,000.00	\$66,000.00
486		1.3.1.3.5	Cooling system production	Mon 6/4/12	Mon 9/3/12	MIT	\$11,538.12	No	4	6	4	8	2	2	32	\$3,692.20	\$15,230.32
487		1.3.1.3.3	Ladders	Mon 10/3/11	Fri 9/28/12	MIT	\$160,000.00	No	6	3	8	8	2	2	34	\$54,400.00	\$214,400.00
488		1.3.2	Electronics	Fri 10/1/10	Fri 3/29/13	MIT	\$1,186,403.52	No	0	0	0	0	0	0	0	\$310,120.40	\$1,496,523.92
489		1.3.2.1	Electrical Design and Requirements	Fri 10/1/10	Fri 12/31/10	MIT	\$98,801.12	No	0	0	0	0	0	0	0	\$35,568.40	\$134,369.52
490		1.3.2.1.1	Sensors	Fri 10/1/10	Fri 10/29/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
491		1.3.2.1.2	Readout Chips	Fri 10/1/10	Fri 10/29/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
492		1.3.2.1.3	Flex hybrid	Fri 10/1/10	Tue 11/30/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
493		1.3.2.1.4	Readout system	Fri 10/1/10	Fri 12/31/10	MIT	\$71,026.56	No	0	0	0	0	0	0	0	\$25,569.56	\$96,596.12
494		1.3.2.1.4.1	Crates	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
495		1.3.2.1.4.2	Data transmitters	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
496		1.3.2.1.4.3	APV Readout Modules	Fri 10/1/10	Fri 12/31/10	MIT	\$71,026.56	No	8	4	4	8	2	2	36	\$25,569.56	\$96,596.12
497		1.3.2.1.4.4	APV Readout Controllers	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
498		1.3.2.1.4.5	Bias voltage supplies	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
499		1.3.2.1.5	DAQ	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
500		1.3.2.1.5.1	Fibers	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
501		1.3.2.1.5.2	Data receivers	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
502		1.3.2.1.5.3	Computers	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
503		1.3.2.1.6	Slow Controls	Fri 10/1/10	Fri 12/31/10	MIT	\$0.00	No	0	0	0	0	0	0	0	\$0.00	\$0.00
504		1.3.2.1.7	On project labor	Fri 10/1/10	Tue 11/30/10	MIT	\$27,774.56	No	8	4	4	8	2	2	36	\$9,998.84	\$37,773.40
505		1.3.2.2	Electrical Prototypes Production	Fri 10/1/10	Fri 4/1/11	MIT	\$125,300.00	No	0	0	0	0	0	0	0	\$25,627.00	\$150,927.00
506		1.3.2.2.1	Prototype sensor drawings and masks	Fri 10/1/10	Wed 12/1/10	MIT	\$67,500.00	No	4	3	8	0	2	1	19	\$12,825.00	\$80,325.00
507		1.3.2.2.2	Prototype sensors production	Thu 12/2/10	Tue 3/1/11	MIT	\$43,800.00	No	4	3	8	0	2	1	19	\$8,322.00	\$52,122.00
508		1.3.2.2.3	Prototype flex hybrid production	Fri 10/1/10	Fri 4/1/11	MIT	\$14,000.00	No	8	4	8	4	2	1	32	\$4,480.00	\$18,480.00
509		1.3.2.3	Electrical Procurement/Fabrication	Fri 10/1/10	Fri 3/29/13	MIT	\$962,302.40	No	0	0	0	0	0	0	0	\$248,924.99	\$1,211,227.39
510		1.3.2.3.1	Sensors procurement	Mon 10/3/11	Fri 9/28/12	MIT	\$334,464.00	No	4	3	8	0	2	1	19	\$63,548.16	\$398,012.16
511		1.3.2.3.3	Readout Chips	Fri 10/1/10	Fri 9/30/11	MIT	\$30,000.00	No	1	1	2	0	2	1	5	\$1,500.00	\$31,500.00
512		1.3.2.3.4	Flex hybrid procurement	Tue 10/4/11	Tue 10/2/12	MIT	\$230,400.00	No	8	4	8	4	4	1	48	\$110,592.00	\$340,992.00
513		1.3.2.3.5	Cables	Mon 10/1/12	Fri 3/29/13	MIT	\$52,200.00	No	0	0	0	0	0	0	0	\$7,308.00	\$59,508.00
514		1.3.2.3.5.1	Signal cables inside field cage	Mon 10/1/12	Fri 3/29/13	MIT	\$13,800.00	No	1	4	4	4	2	1	14	\$1,932.00	\$15,732.00
515		1.3.2.3.5.2	Signal cables outside field cage	Mon 10/1/12	Fri 3/29/13	MIT	\$28,800.00	No	1	4	4	4	2	1	14	\$4,032.00	\$32,832.00
516		1.3.2.3.5.3	Bias voltage cables outside field cage	Mon 10/1/12	Fri 3/29/13	MIT	\$9,600.00	No	1	4	4	4	2	1	14	\$1,344.00	\$10,944.00

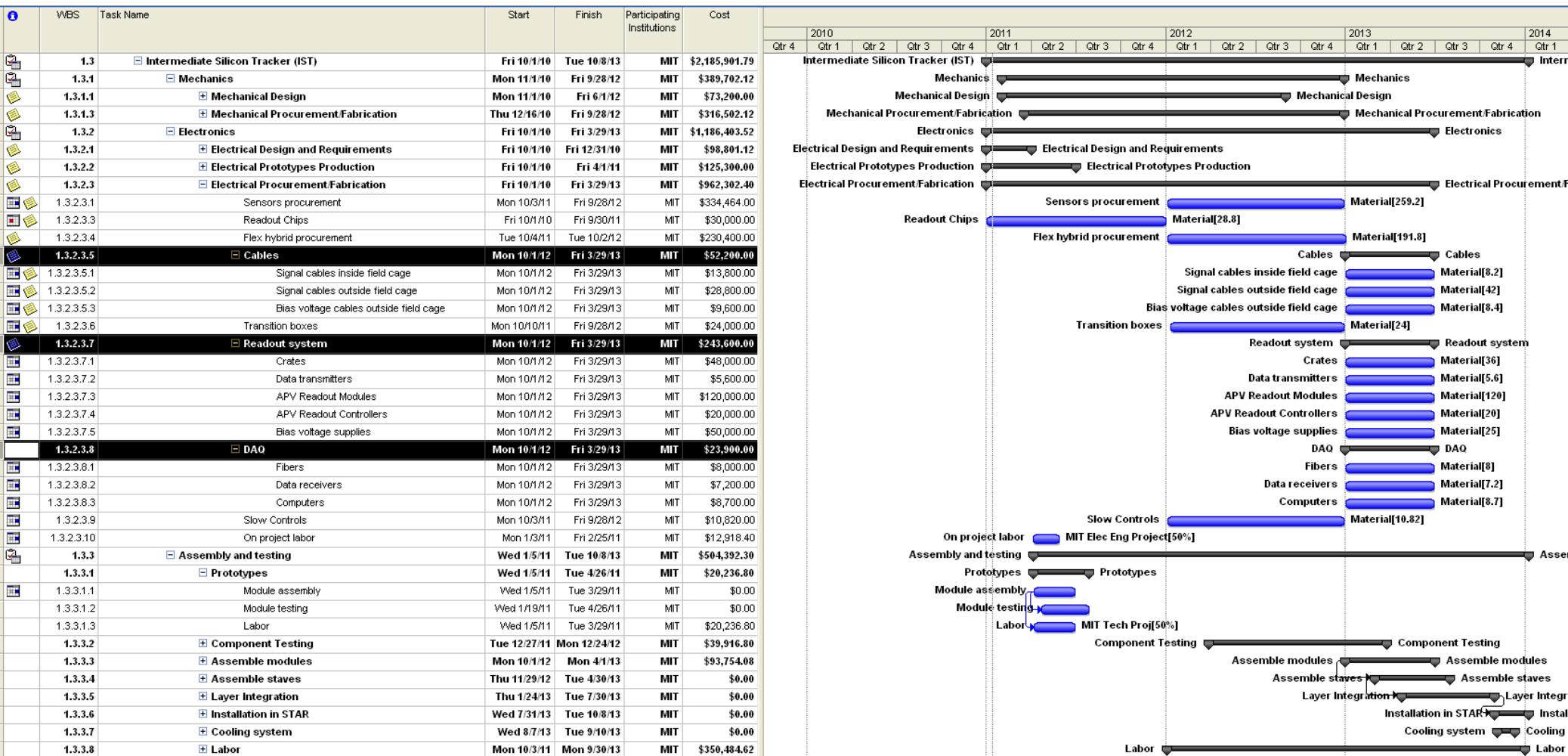
# IST WBS: Early critical path



# IST WBS: Early cost, i.e. FYnow



# IST WBS: FY12 redistribution



# IST: Scope change => plans

- 1 hybrid per ladder instead of 3
  - laminate hybrid directly to ladder
  - no more 'curling' modules
  - simpler and less cables
- 
- proof of principle lamination
  - ladder mechanical and bonding tests
  - large hybrid design/production
  - 6 sensor ladder prototype by May 2011

# IST: Tech report October

A quotation has been received for a dummy large IST hybrid. This dummy should closely mimic the real large hybrid of which the design has not been finished yet. It should have the same number of kapton layers, realistic copper traces and bondable gold in designated areas. The dummy will be laminated to a prototype IST ladder to study the feasibility of this process and to determine if reliable wire bonding is possible to the assembly. This step should be done as soon as possible to be able to finalize the large hybrid and ladder design. Unfortunately the quotation came out a bit higher than expected for a pretty much blank dummy and other vendors are being contacted.

The specifications of the IST sensors were discussed in person with the local Hamamatsu representative, no issues were found. The rough estimate of a 6 month prototype production was reconfirmed. The representative did warn for a slight price increase due to less favorable yen-dollar exchange rates.

The testing of the APV readout chips is ongoing with both the IST pre-prototype and the FGT readout boards. Although the FGT is a different project, it shares an almost identical readout chain with the IST. Because of higher priorities for the FGT project there is a delay in the writing of the calibration code for the IST test readout of the pre-prototype. Hopefully this will be finished in October. The issues with unreliable I2C seem to have been resolved by issuing a hard reset when the APV chips get powered up. Grounding studies are done for the FGT readout boards using the analysis code developed for the IST pre-prototype.

# IST: Tech report October

The IST readout system consists of an Wiener MPod crates, APV Readout Modules (ARM's) and APV Readout Controllers (ARC's). The first ARC's, which accept STAR triggers and provide the interface between DAQ and the ARM's, have been produced and testing will begin shortly.

The full design of the ARM has to be finalized still. However, the interfacing with the APV front-ends through a long readout cable is being tested successfully already. This interface provides power to the APV chips but also does optimal filtering of the signals which get distorted by the long signal cable. The first prototypes for the ARM are expected before the end of CY2010.

To be able to test a simple readout chain (APV board, cable and readout crate with ARM's and ARC's) during STAR operation this year cables were already installed in STAR.